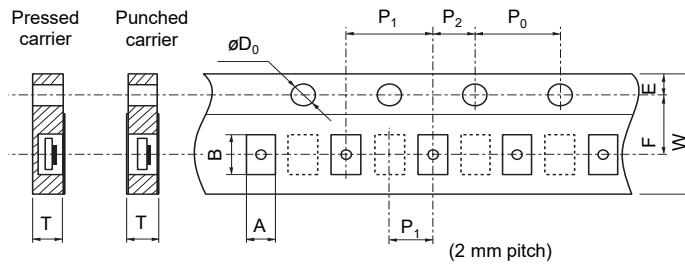


Packaging methods (Taping)

● Standard quantity

Part number	Size (inch)	Type	Kind of taping	Pitch (P ₁) (mm)	Quantity (pcs / reel)
EZAEG1N	0201	Single	Pressed carrier taping	2	15000
EZAEG2A,2N	0402				10000
EZAEG3A	0603		Punched carrier taping	4	5000
EZAEG3W	0603				4000
EZAEGCA	0805	Array			5000

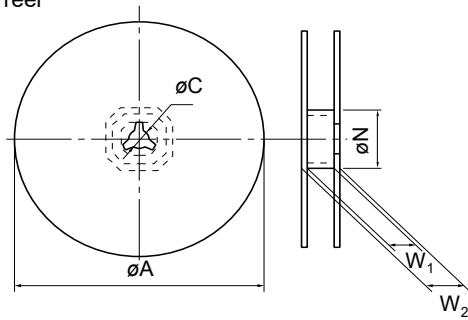
● Carrier taping



Unit : mm											
Part number	Size(inch)	A	B	W	F	E	P ₁	P ₂	P ₀	øD ₀	T
EZAEG1N	0201	0.38±0.05	0.68±0.05	8.00±0.20	3.50±0.05	1.75±0.10	2.00±0.10	2.00±0.05	4.00±0.10	1.5 ^{+0.1} ₀	0.42±0.05
EZAEG2A,2N	0402	0.70±0.05	1.20±0.05				0.60±0.05				
EZAEG3A	0603	1.10±0.10	1.90±0.10				0.70±0.05				
EZAEG3W	0603	0.91±0.10	1.82±0.10				1.08±0.10				
EZAEGCA	0805	1.55±0.15	2.30±0.20				0.85±0.05				

Unit : mm

● Taping reel



Dimensions		
øA	øN	øC
180.0 ⁰ _{-1.5}	60.0 ^{+1.0} ₀	13.0±0.2

Dimensions	
W ₁	W ₂
9.0 ^{+1.0} ₀	11.4±1.0

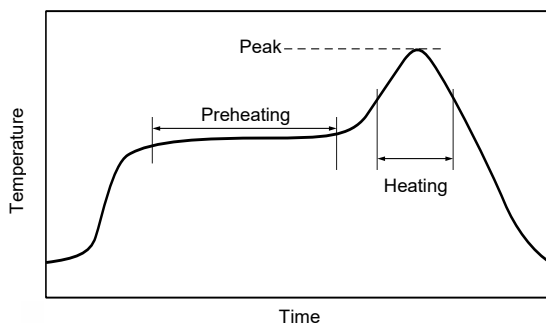
Unit : mm

Recommended soldering conditions

Recommendations and precautions are described below

● Recommended soldering conditions for reflow

- Reflow soldering shall be performed a maximum of two times.
- Please contact us for additional information when used in conditions other than those specified.
- Please measure the temperature of the terminals and study every kind of solder and printed circuit board for solderability before actual use.



For soldering (Example : Sn/Pb)

	Temperature	Time
Preheating	140 °C to 160 °C	60 s to 120 s
Main heating	Above 200 °C	30 s to 40 s
Peak	235 ± 5 °C	max. 10 s

For lead-free soldering (Example : Sn/Ag/Cu)

	Temperature	Time
Preheating	150 °C to 180 °C	60 s to 120 s
Main heating	Above 230 °C	30 s to 40 s
Peak	max. 260 °C	max. 10 s